

IN THE SPECIFICATION

Please amend the Title on page 1 as follows:

~~SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF~~
INCLUDING FORMING ADDITIONAL ACTIVE LAYER

Please insert the following paragraph at page 1, between lines 4 and 5:

This application is based upon and claims the benefit of priority from the prior Japanese Patent Application No. 2002-327766, filed November 12, 2002, and from U.S. Application No. 10/444,959, filed May 27, 2003, the entire contents of which are incorporated herein by reference.